

512K x 8 HIGH-SPEED CMOS STATIC RAM

APRIL 2005

FEATURES

- High-speed access times:
10, 12 ns
- High-performance, low-power CMOS process
- Multiple center power and ground pins for greater noise immunity
- Easy memory expansion with \overline{CE} and \overline{OE} options
- \overline{CE} power-down
- Fully static operation: no clock or refresh required
- TTL compatible inputs and outputs
- Single 3.3V power supply
- Packages available:
 - 36-pin 400-mil SOJ
 - 36-pin miniBGA
 - 44-pin TSOP (Type II)
- Lead-free available

DESCRIPTION

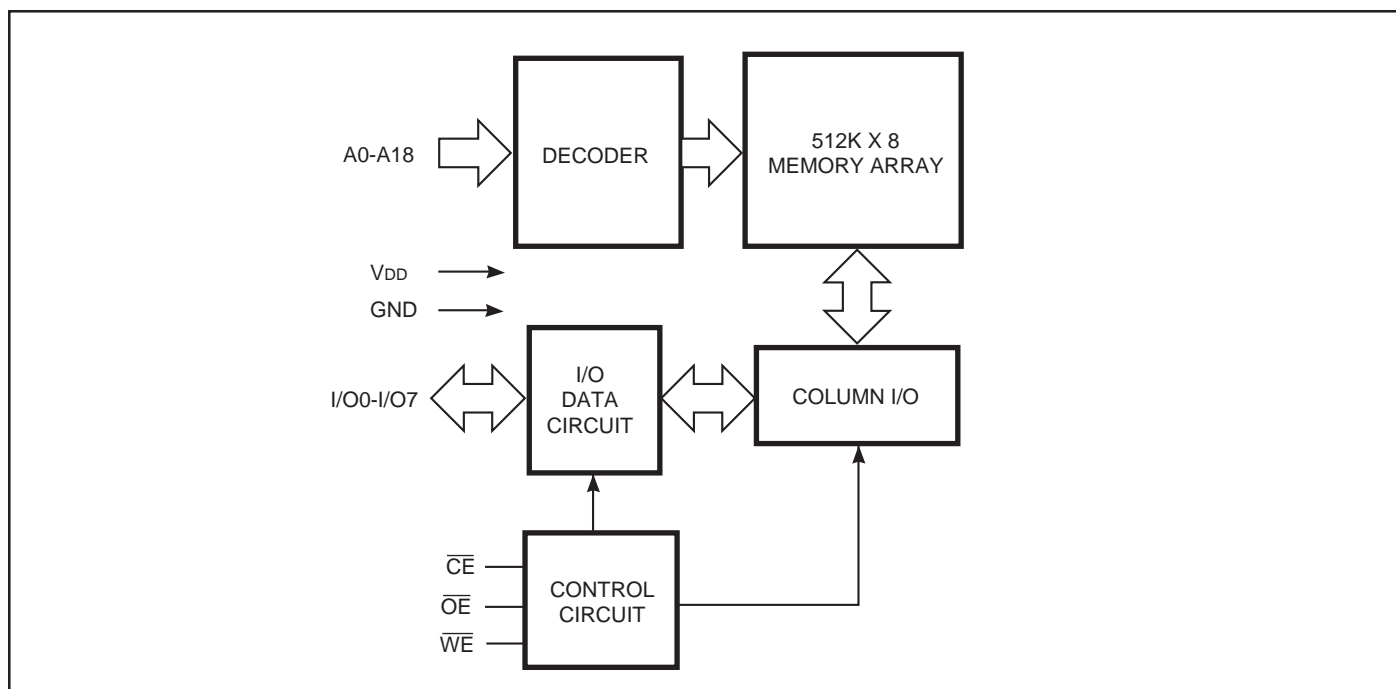
The *ISSI* IS61LV5128AL is a very high-speed, low power, 524,288-word by 8-bit CMOS static RAM. The IS61LV5128AL is fabricated using *ISSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields higher performance and low power consumption devices.

When \overline{CE} is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down to 250 μ W (typical) with CMOS input levels.

The IS61LV5128AL operates from a single 3.3V power supply and all inputs are TTL-compatible.

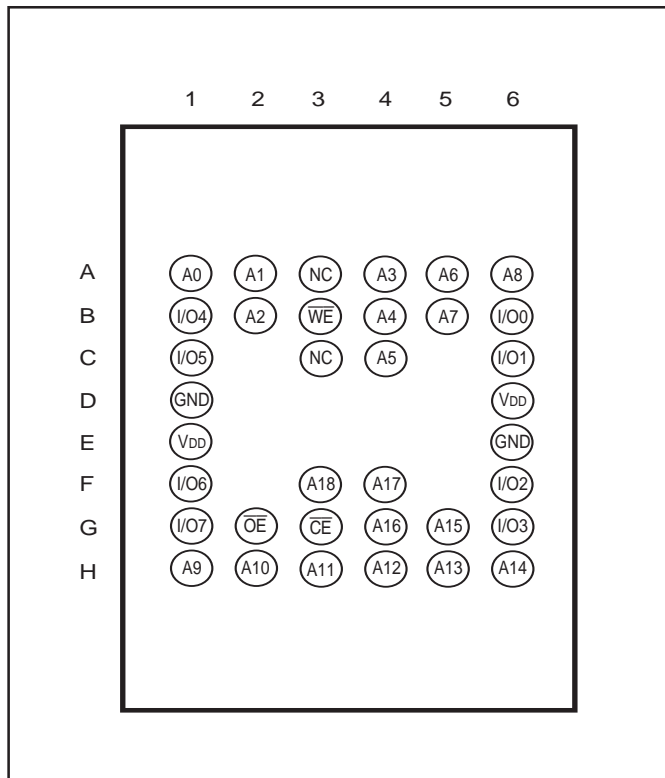
The IS61LV5128AL is available in 36-pin 400-mil SOJ, 36-pin mini BGA, and 44-pin TSOP (Type II) packages.

FUNCTIONAL BLOCK DIAGRAM

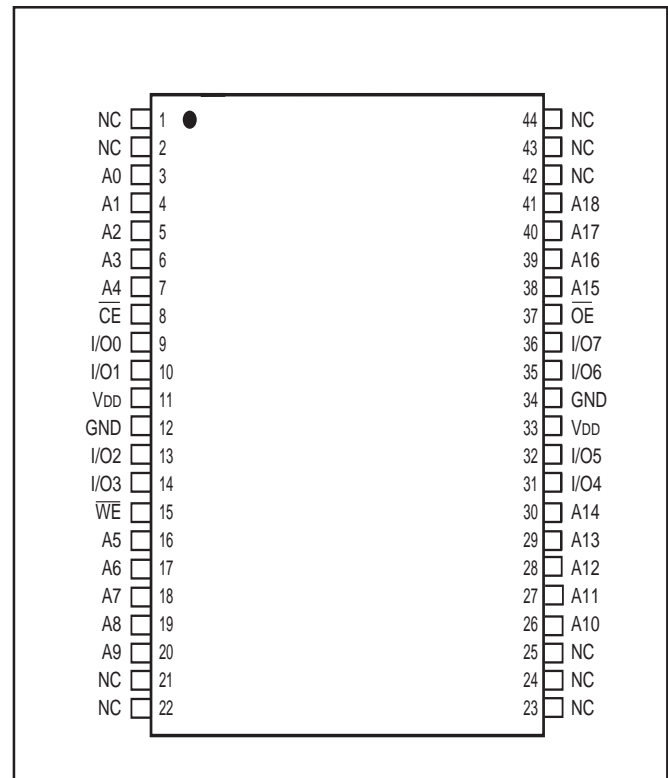


Copyright © 2005 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

PIN CONFIGURATION
36 mini BGA



44-Pin TSOP (Type II)



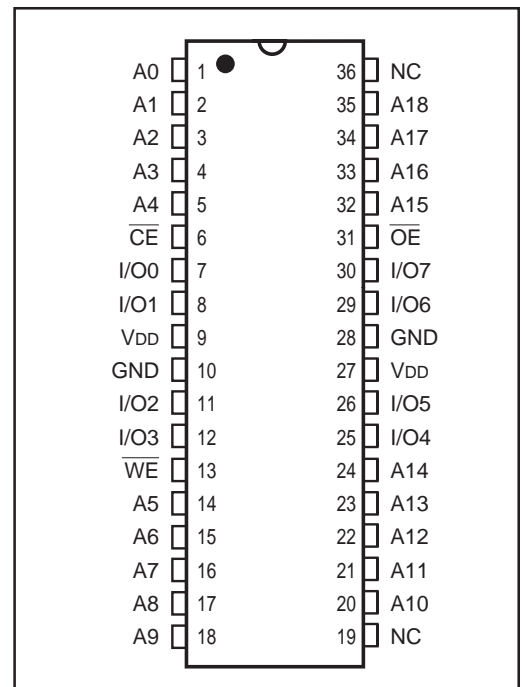
PIN DESCRIPTIONS

A0-A18	Address Inputs
CE	Chip Enable Input
OE	Output Enable Input
WE	Write Enable Input
I/O0-I/O7	Bidirectional Ports
VDD	Power
GND	Ground
NC	No Connection

TRUTH TABLE

Mode	WE	CE	OE	I/O Operation	VDD Current
Not Selected (Power-down)	X	H	X	High-Z	Isb1, Isb2
Output Disabled	H	L	H	High-Z	Icc
Read	H	L	L	DOUT	Icc
Write	L	L	X	DIN	Icc

36-Pin SOJ



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit
V _{TERM}	Terminal Voltage with Respect to GND	-0.5 to V _{DD} + 0.5	V
T _{STG}	Storage Temperature	-65 to +150	°C
P _T	Power Dissipation	1.0	W

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

OPERATING RANGE

Range	Ambient Temperature	V _{DD}	
		10ns	12ns
Commercial	0°C to +70°C	3.3V +10%, -5%	3.3V ±10%
Industrial	-40°C to +85°C	3.3V +10%, -5%	3.3V ±10%

CAPACITANCE^(1,2)

Symbol	Parameter	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	6	pF
C _{I/O}	Input/Output Capacitance	V _{OUT} = 0V	8	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T_A = 25°C, f = 1 MHz, V_{DD} = 3.3V.

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit	
V _{OH}	Output HIGH Voltage	V _{DD} = Min., I _{OH} = -4.0 mA	2.4	—	V	
V _{OL}	Output LOW Voltage	V _{DD} = Min., I _{OL} = 8.0 mA	—	0.4	V	
V _{IH}	Input HIGH Voltage		2.0	V _{DD} + 0.3	V	
V _{IL}	Input LOW Voltage ⁽¹⁾		-0.3	0.8	V	
I _{LI}	Input Leakage	GND ≤ V _{IN} ≤ V _{DD}	Com. Ind.	-2 5	2 5	μA
I _{LO}	Output Leakage	GND ≤ V _{OUT} ≤ V _{DD} , Outputs Disabled	Com. Ind.	-2 -5	2 5	μA

Note:

1. V_{IL} = -3.0V for pulse width less than 10 ns.

POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	Test Conditions	-10		-12		Unit
			Min.	Max.	Min.	Max.	
I _{CC}	V _{DD} Dynamic Operating Supply Current	V _{DD} = Max., I _{OUT} = 0 mA, f = f _{MAX}	Com. Ind.	— 90 95	— 85 90	mA	
I _{SB}	TTL Standby Current (TTL Inputs)	V _{DD} = Max., V _{IN} = V _{IH} or V _{IL} $\overline{CE} \geq V_{IH}$, f = f _{MAX} .	Com. Ind.	— 40 45	— 35 40	mA	
I _{SB1}	TTL Standby Current (TTL Inputs)	V _{DD} = Max., V _{IN} = V _{IH} or V _{IL} $\overline{CE} \geq V_{IH}$, f = 0	Com. Ind.	— 20 25	— 20 25	mA	
I _{SB2}	CMOS Standby Current (CMOS Inputs)	V _{DD} = Max., $\overline{CE} \geq V_{DD} - 0.2V$, V _{IN} ≥ V _{DD} - 0.2V, or V _{IN} ≤ 0.2V, f = 0	Com. Ind.	— 15 20	— 15 20	mA	

Note:

1. At f = f_{MAX}, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

READ CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

Symbol	Parameter	-10		-12		Unit
		Min.	Max.	Min.	Max.	
t _{RC}	Read Cycle Time	10	—	12	—	ns
t _{AA}	Address Access Time	—	10	—	12	ns
t _{OH}	Output Hold Time	2	—	2	—	ns
t _{ACE}	$\overline{\text{CE}}$ Access Time	—	10	—	12	ns
t _{DOE}	$\overline{\text{OE}}$ Access Time	—	4	—	5	ns
t _{HZOE} ⁽²⁾	$\overline{\text{OE}}$ to High-Z Output	—	4	—	5	ns
t _{LZOE} ⁽²⁾	$\overline{\text{OE}}$ to Low-Z Output	0	—	0	—	ns
t _{HZCE} ⁽²⁾	$\overline{\text{CE}}$ to High-Z Output	0	4	0	6	ns
t _{LZCE} ⁽²⁾	$\overline{\text{CE}}$ to Low-Z Output	3	—	3	—	ns
t _{PU}	Power Up Time	0	—	0	—	ns
t _{PD}	Power Down Time	—	10	—	12	ns

Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage.

AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	3 ns
Input and Output Timing and Reference Levels	1.5V
Output Load	See Figures 1 and 2

AC TEST LOADS

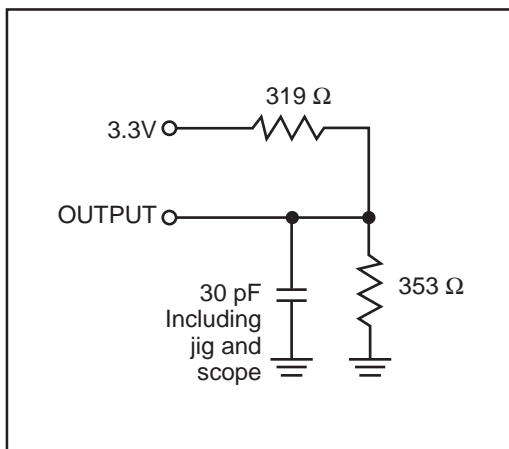


Figure 1

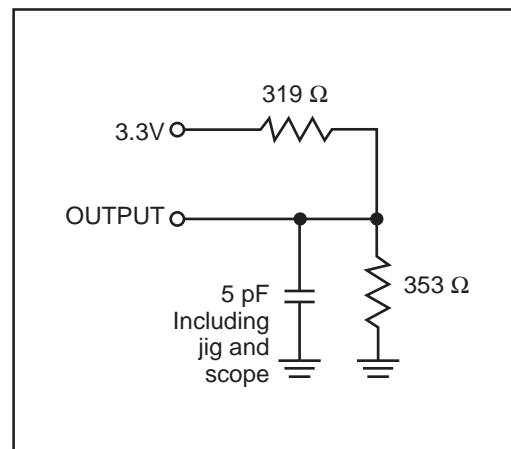
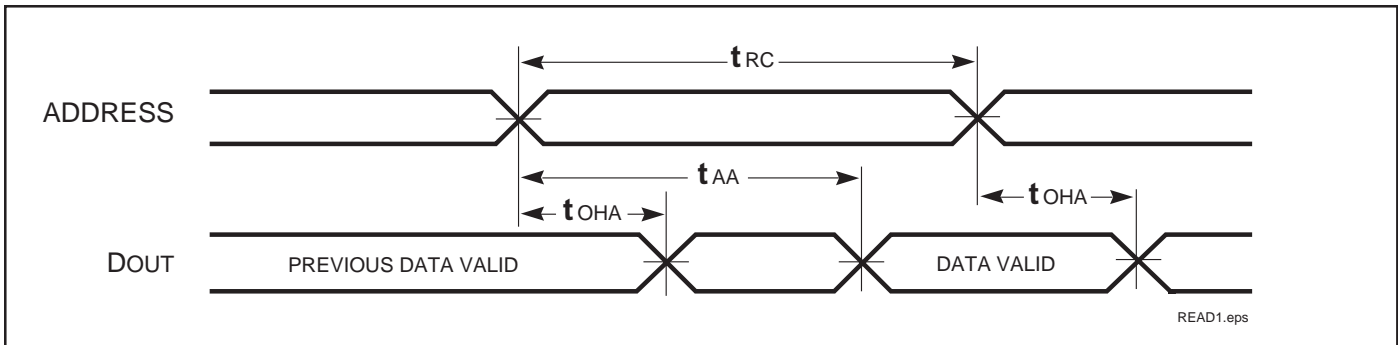


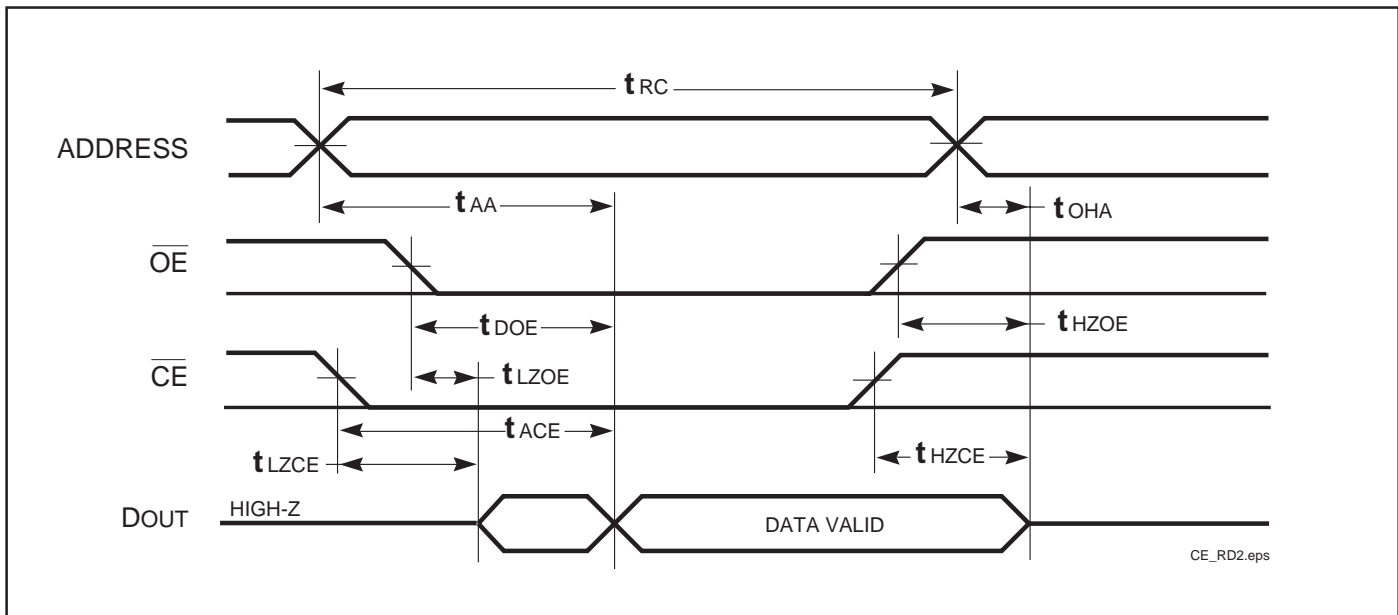
Figure 2

AC WAVEFORMS

READ CYCLE NO. 1^(1,2) (Address Controlled) ($\overline{CE} = \overline{OE} = V_{IL}$)



READ CYCLE NO. 2^(1,3) (\overline{CE} and \overline{OE} Controlled)



Notes:

1. \overline{WE} is HIGH for a Read Cycle.
2. The device is continuously selected. $\overline{OE}, \overline{CE} = V_{IL}$.
3. Address is valid prior to or coincident with \overline{CE} LOW transitions.

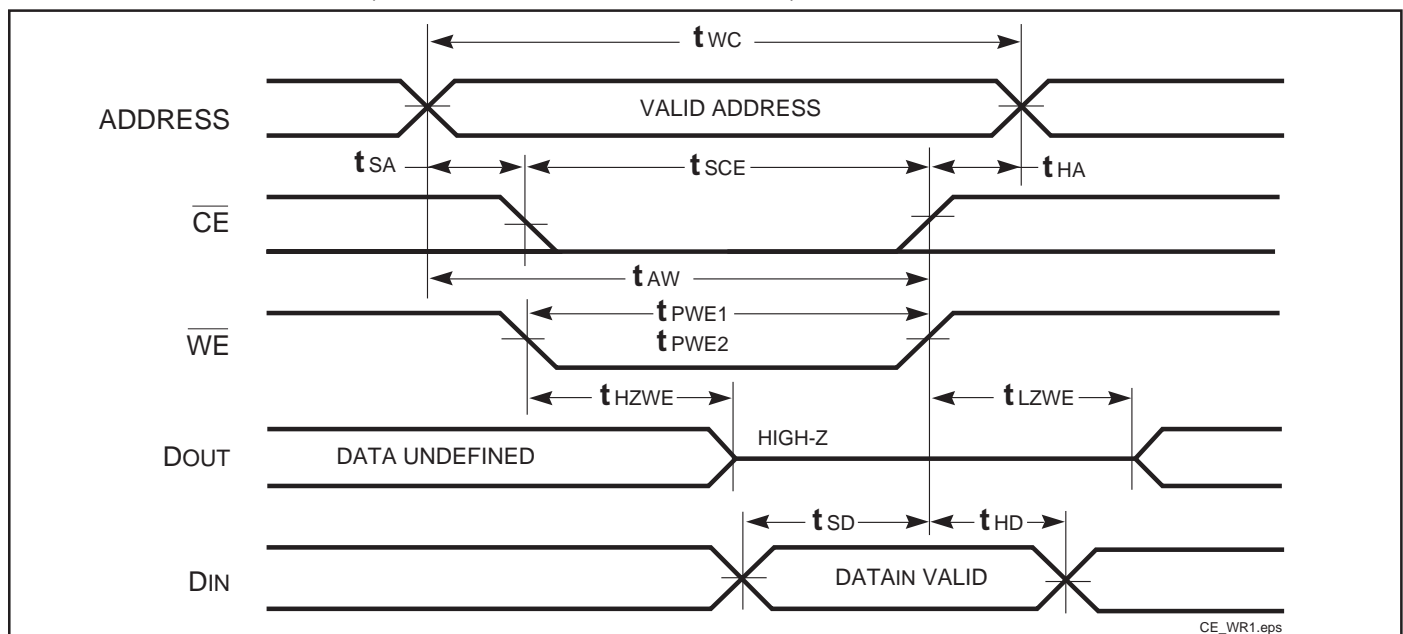
WRITE CYCLE SWITCHING CHARACTERISTICS^(1,3) (Over Operating Range)

Symbol	Parameter	-10		-12		Unit																					
		Min.	Max.	Min.	Max.																						
t_{WC}	Write Cycle Time	10	—	12	—	ns																					
t_{SCE}	\overline{CE} to Write End	8	—	8	—	ns																					
t_{AW}	Address Setup Time to Write End	8	—	8	—	ns																					
t_{HA}	Address Hold from Write End	0	—	0	—	ns																					
t_{SA}	Address Setup Time	0	—	0	—	ns																					
t_{PWE1}	\overline{WE} Pulse Width	8	—	8	—	ns																					
t_{PWE2}	\overline{WE} Pulse Width (\overline{OE} = LOW)	10	—	12	—	ns																					
t_{SD}	Data Setup to Write End	6	—	6	—	ns </tr <tr> <td>t_{HD}</td> <td>Data Hold from Write End</td> <td>0</td> <td>—</td> <td>0</td> <td>—</td> <td>ns</td> </tr> <tr> <td>$t_{HZWE}^{(2)}$</td> <td>\overline{WE} LOW to High-Z Output</td> <td>—</td> <td>5</td> <td>—</td> <td>6</td> <td>ns</td> </tr> <tr> <td>$t_{LZWE}^{(2)}$</td> <td>\overline{WE} HIGH to Low-Z Output</td> <td>2</td> <td>—</td> <td>2</td> <td>—</td> <td>ns</td> </tr>	t_{HD}	Data Hold from Write End	0	—	0	—	ns	$t_{HZWE}^{(2)}$	\overline{WE} LOW to High-Z Output	—	5	—	6	ns	$t_{LZWE}^{(2)}$	\overline{WE} HIGH to Low-Z Output	2	—	2	—	ns
t_{HD}	Data Hold from Write End	0	—	0	—	ns																					
$t_{HZWE}^{(2)}$	\overline{WE} LOW to High-Z Output	—	5	—	6	ns																					
$t_{LZWE}^{(2)}$	\overline{WE} HIGH to Low-Z Output	2	—	2	—	ns																					

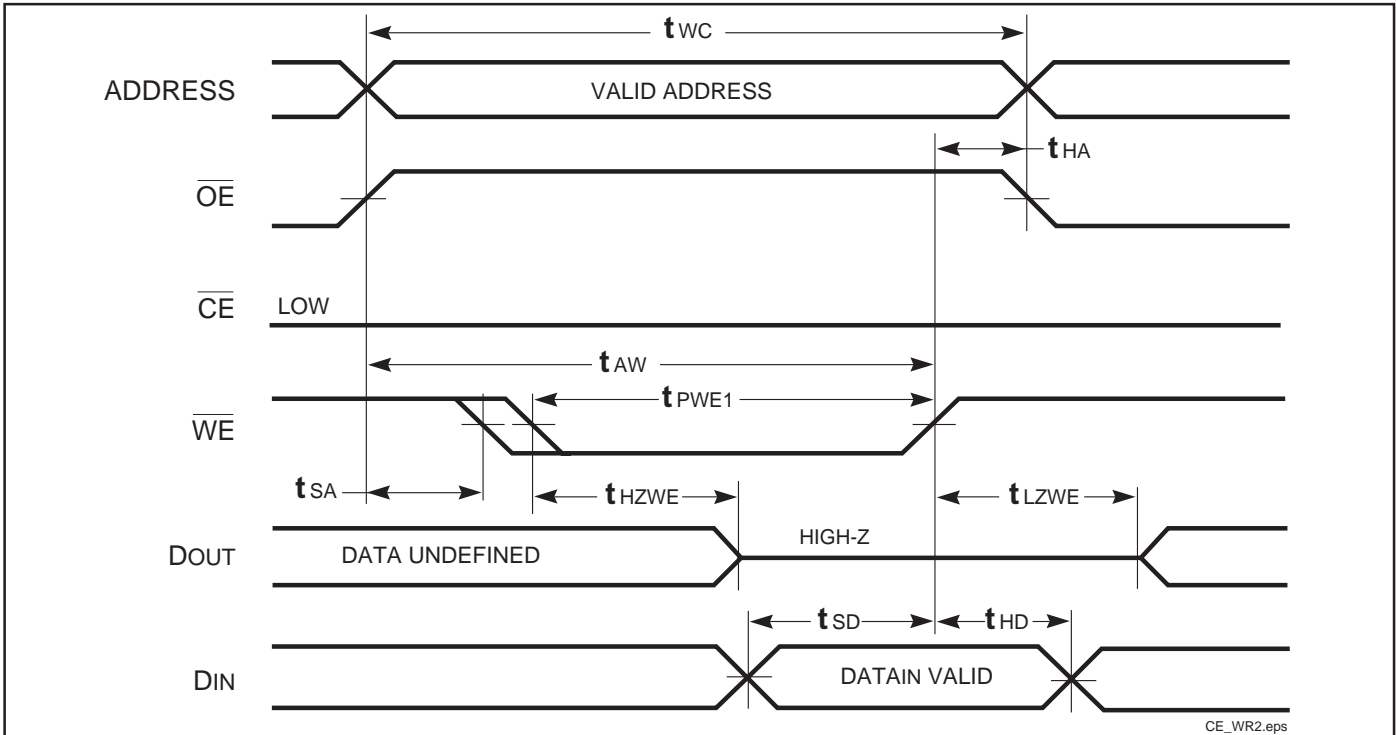
Notes:

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ± 500 mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of \overline{CE} LOW and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.

AC WAVEFORMS

WRITE CYCLE NO. 1^(1,2) (\overline{CE} Controlled, \overline{OE} = HIGH or LOW)

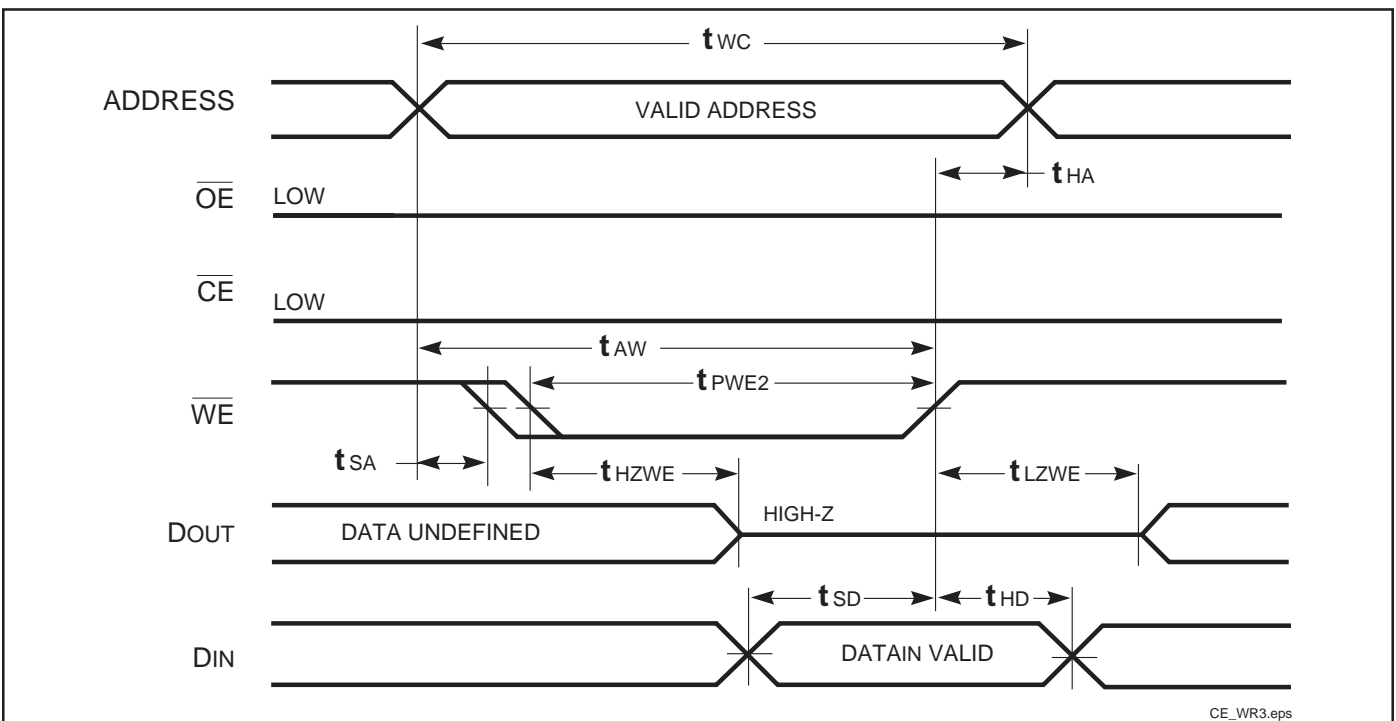
WRITE CYCLE NO. 2^(1,2) (\overline{WE} Controlled: \overline{OE} is HIGH During Write Cycle)



Notes:

1. The internal write time is defined by the overlap of \overline{CE} LOW and \overline{WE} LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if $\overline{OE} > V_{IH}$.

WRITE CYCLE NO. 3 (\overline{WE} Controlled: \overline{OE} is LOW During Write Cycle)



ORDERING INFORMATION**Commercial Range: 0°C to +70°C**

Speed (ns)	Order Part No.	Package
10	IS61LV5128AL-10K	400-mil Plastic SOJ
10	IS61LV5128AL-10T	TSOP (Type II)
12	IS61LV5128AL-12K	400-mil Plastic SOJ
12	IS61LV5128AL-12T	TSOP (Type II)

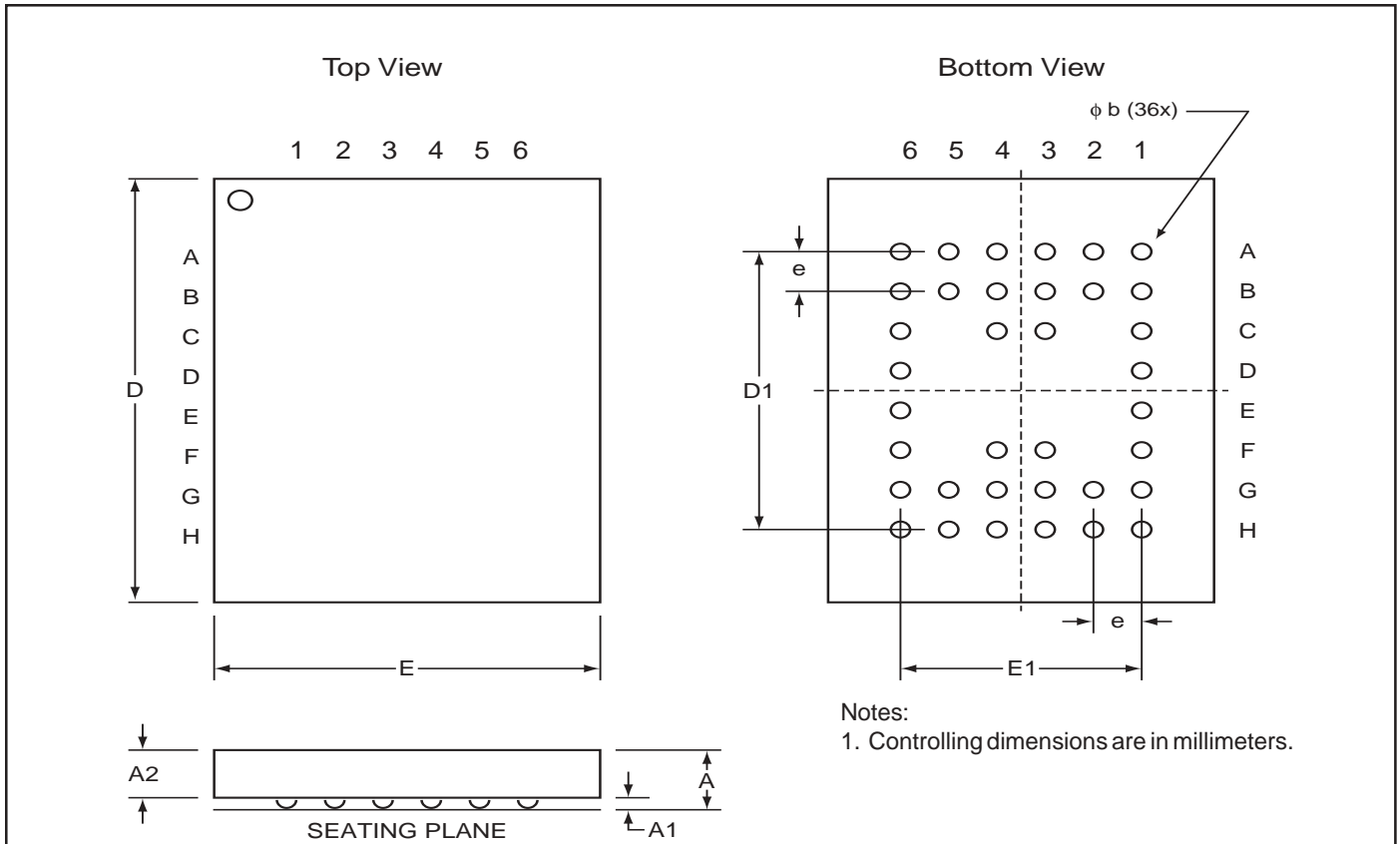
Industrial Range: -40°C to +85°C

Speed (ns)	Order Part No.	Package
10	IS61LV5128AL-10KI	400-mil Plastic SOJ
10	IS61LV5128AL-10KLI	400-mil Plastic SOJ, Lead-free
10	IS61LV5128AL-10TI	TSOP (Type II)
10	IS61LV5128AL-10TLI	TSOP (Type II), Lead-free
10	IS61LV5128AL-10BI	mini BGA (8mmx10mm)
10	IS61LV5128AL-10BLI	mini BGA (8mmx10mm), Lead-free
12	IS61LV5128AL-12TI	TSOP (Type II)

PACKAGING INFORMATION



Mini Ball Grid Array Package Code: B (36-pin)



mBGA - 6mm x 8mm

	MILLIMETERS			INCHES			
	Sym.	Min.	Typ.	Max.	Min.	Typ.	Max.
N0. Leads		36			36		
A	—	—	1.20	—	—	0.047	
A1	0.24	—	0.30	0.009	—	0.012	
A2	0.60	—	—	0.024	—	—	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D1		5.25BSC		0.207BSC			
E	5.90	6.00	6.10	0.232	0.236	0.240	
E1		3.75BSC		0.148BSC			
e		0.75BSC		0.030BSC			
b	0.30	0.35	0.40	0.012	0.014	0.016	

mBGA - 8mm x 10mm

	MILLIMETER			INCHES			
	Sym.	Min.	Typ.	Max.	Min.	Typ.	Max.
N0. Leads		36			36		
A	—	—	1.20	—	—	0.047	
A1	0.24	—	0.30	0.009	—	0.012	
A2	0.60	—	—	0.024	—	—	
D	9.90	10.00	10.10	0.390	0.394	0.398	
D1		5.25BSC		.207BSC			
E	7.90	8.00	8.10	0.311	0.315	0.319	
E1		3.75BSC		0.148BSC			
e		0.75BSC		0.030BSC			
b	0.30	0.35	0.40	0.012	0.014	0.016	

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

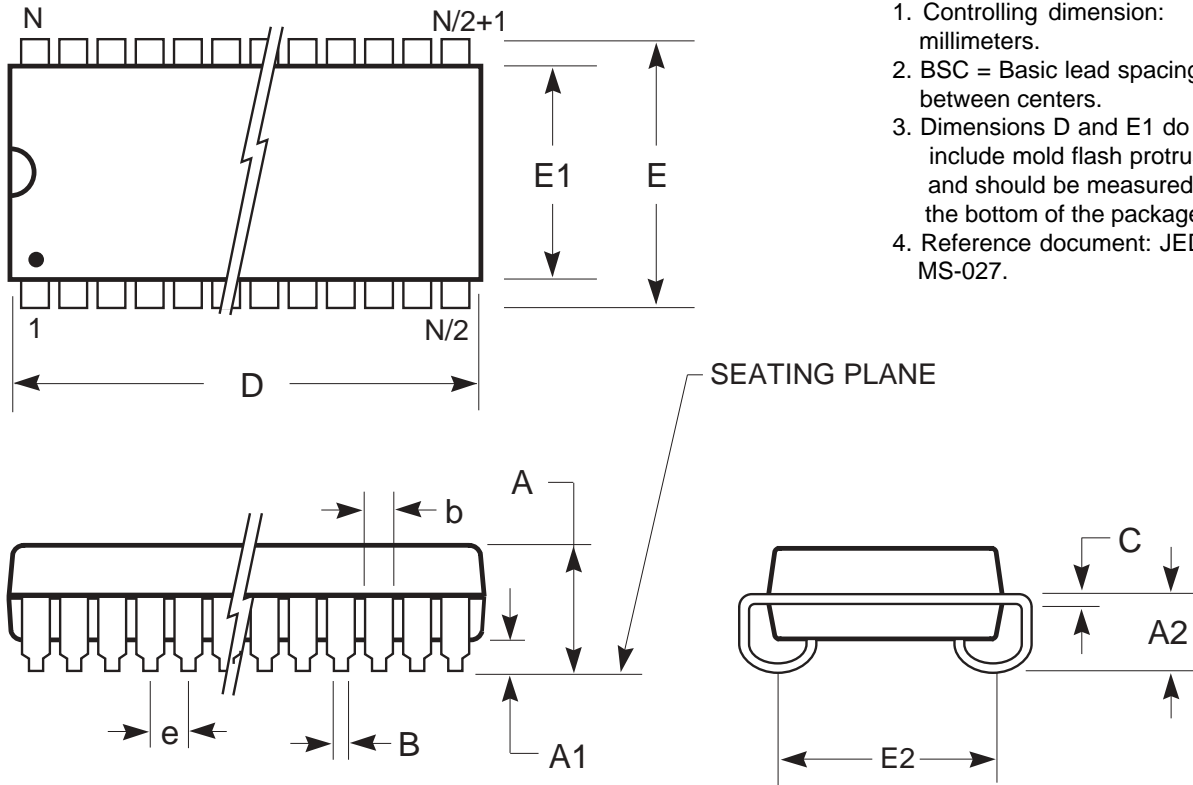
Integrated Silicon Solution, Inc. — www.issi.com — 1-800-379-4774

Rev. E
01/15/03

PACKAGING INFORMATION

400-mil Plastic SOJ

Package Code: K



Notes:

1. Controlling dimension: millimeters.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Reference document: JEDEC MS-027.

Symbol	Millimeters		Inches		Millimeters		Inches		Millimeters		Inches	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
No. Leads (N)	28				32				36			
A	3.25	3.75	0.128	0.148	3.25	3.75	0.128	0.148	3.25	3.75	0.128	0.148
A1	0.64	—	0.025	—	0.64	—	0.025	—	0.64	—	0.025	—
A2	2.08	—	0.082	—	2.08	—	0.082	—	2.08	—	0.082	—
B	0.38	0.51	0.015	0.020	0.38	0.51	0.015	0.020	0.38	0.51	0.015	0.020
b	0.66	0.81	0.026	0.032	0.66	0.81	0.026	0.032	0.66	0.81	0.026	0.032
C	0.18	0.33	0.007	0.013	0.18	0.33	0.007	0.013	0.18	0.33	0.007	0.013
D	18.29	18.54	0.720	0.730	20.82	21.08	0.820	0.830	23.37	23.62	0.920	0.930
E	11.05	11.30	0.435	0.445	11.05	11.30	0.435	0.445	11.05	11.30	0.435	0.445
E1	10.03	10.29	0.395	0.405	10.03	10.29	0.395	0.405	10.03	10.29	0.395	0.405
E2	9.40 BSC		0.370 BSC		9.40 BSC		0.370 BSC		9.40 BSC		0.370 BSC	
e	1.27 BSC		0.050 BSC		1.27 BSC		0.050 BSC		1.27 BSC		0.050 BSC	

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

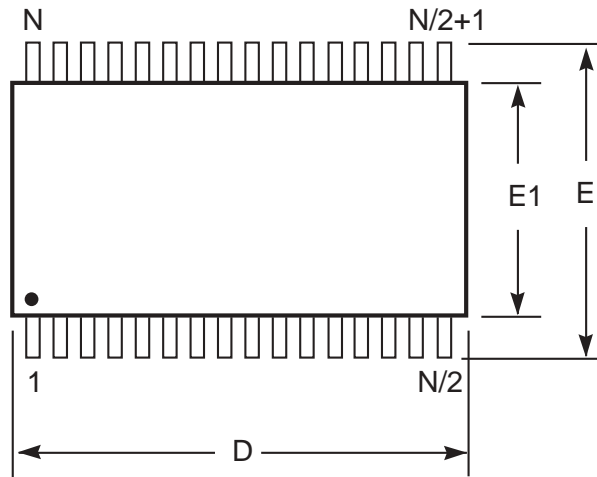
Symbol	Millimeters		Inches		Millimeters		Inches		Millimeters		Inches	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
No. Leads (N)	40				42				44			
A	3.25	3.75	0.128	0.148	3.25	3.75	0.128	0.148	3.25	3.75	0.128	0.148
A1	0.64	—	0.025	—	0.64	—	0.025	—	0.64	—	0.025	—
A2	2.08	—	0.082	—	2.08	—	0.082	—	2.08	—	0.082	—
B	0.38	0.51	0.015	0.020	0.38	0.51	0.015	0.020	0.38	0.51	0.015	0.020
b	0.66	0.81	0.026	0.032	0.66	0.81	0.026	0.032	0.66	0.81	0.026	0.032
C	0.18	0.33	0.007	0.013	0.18	0.33	0.007	0.013	0.18	0.33	0.007	0.013
D	25.91	26.16	1.020	1.030	27.18	27.43	1.070	1.080	28.45	28.70	1.120	1.130
E	11.05	11.30	0.435	0.445	11.05	11.30	0.435	0.445	11.05	11.30	0.435	0.445
E1	10.03	10.29	0.395	0.405	10.03	10.29	0.395	0.405	10.03	10.29	0.395	0.405
E2	9.40 BSC		0.370 BSC		9.40 BSC		0.370 BSC		9.40 BSC		0.370 BSC	
e	1.27 BSC		0.050 BSC		1.27 BSC		0.050 BSC		1.27 BSC		0.050 BSC	

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

PACKAGING INFORMATION

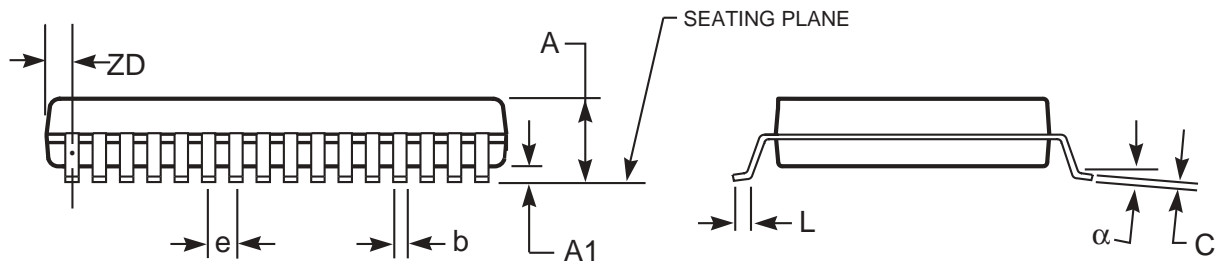


Plastic TSOP Package Code: T (Type II)



Notes:

1. Controlling dimension: millimeters, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within 0.004 inches at the seating plane.



Plastic TSOP (T - Type II)

Symbol	Millimeters		Inches		Millimeters		Inches		Millimeters		Inches	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max
Ref. Std.												
No. Leads (N)	32				44				50			
A	—	1.20	—	0.047	—	1.20	—	0.047	—	1.20	—	0.047
A1	0.05	0.15	0.002	0.006	0.05	0.15	0.002	0.006	0.05	0.15	0.002	0.006
b	0.30	0.52	0.012	0.020	0.30	0.45	0.012	0.018	0.30	0.45	0.012	0.018
C	0.12	0.21	0.005	0.008	0.12	0.21	0.005	0.008	0.12	0.21	0.005	0.008
D	20.82	21.08	0.820	0.830	18.31	18.52	0.721	0.729	20.82	21.08	0.820	0.830
E1	10.03	10.29	0.391	0.400	10.03	10.29	0.395	0.405	10.03	10.29	0.395	0.405
E	11.56	11.96	0.451	0.466	11.56	11.96	0.455	0.471	11.56	11.96	0.455	0.471
e	1.27 BSC		0.050 BSC		0.80 BSC		0.032 BSC		0.80 BSC		0.031 BSC	
L	0.40	0.60	0.016	0.024	0.41	0.60	0.016	0.024	0.40	0.60	0.016	0.024
ZD	0.95 REF		0.037 REF		0.81 REF		0.032 REF		0.88 REF		0.035 REF	
alpha	0°	5°	0°	5°	0°	5°	0°	5°	0°	5°	0°	5°

Copyright © 2003 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.